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JAPANESE PATENT OFFICE

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PATENT ABSTRACTS OF JAPAN

(11) Publication number: 2002086346 A

(43) Date of publication of application: 26.03.02

(51) Int. Cl

B24B 37/00
C03C 19/00
C08G 61/06
C08J 5/14
C08K 5/00
C08L 65/00
G02F 1/13
G02F 1/1333
G11B 5/84
G11B 7/26
H01L 21/304

(21) Application number: 2000276319

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(22) Date of filing: 12.09.00

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(54) POLISHING PAD

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a polishing pad having an appropriate hardness, good durability, less water absorptiveness, and capable of being molded into various shapes easily.

SOLUTION: The polishing pad for the surface of a substance is formed from a resin consisting of an open

ring polymer prepared through metathesis polymerization of ring-form olefin, wherein the resin has a thermal deformation temperature of 90-135°C, a compression modulus of elasticity of 980-2940 MPa, and a water absorptiveness of 0.01-0.25 wt.%, and the resultant pad has an appropriate hardness, good durability and less water absorptiveness, and is unlikely to damage the surface of the substance to be polished.

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